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# Liquid-Gated Ambipolar Transport in Ultrathin Films of a Topological Insulator $\text{Bi}_2\text{Te}_3$

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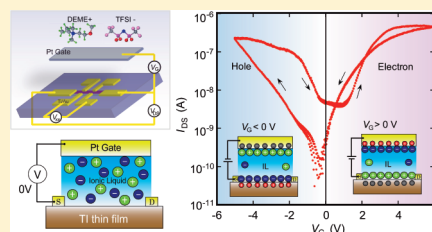
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**S** Supporting Information

**ABSTRACT:** Using ionic-liquid (IL) gating in electric-double-layer transistors (EDLTs), we investigate field-effect electrical transport properties of ultrathin epitaxial films of a topological insulator (TI),  $\text{Bi}_2\text{Te}_3$ . Because of their extreme thinness, the  $\text{Bi}_2\text{Te}_3$  films show a band gap opening and resulting semiconducting transport properties. Near room temperature, an obvious ambipolar transistor operation with an ON-OFF ratio close to  $10^3$  was observed in the transfer characteristics of liquid-gated EDLTs and further confirmed by a sign change of the Hall coefficients. Modulation of the electronic states and a phase transition from a semiconducting conduction ( $dR_{xx}/dT < 0$ ) to a metallic transport ( $dR_{xx}/dT > 0$ ) were observed in the temperature-dependent resistance of the ultrathin  $\text{Bi}_2\text{Te}_3$  channel, demonstrating that the liquid gating is an effective way to modulate the electronic states of TIs.

**KEYWORDS:** Topological insulator, liquid gating, ambipolar transistor, bismuth telluride, electronic transport



As typical Dirac materials with unique band structures where low energy electrons display linear energy-momentum dispersion and can be accurately described by a massless Dirac Hamiltonian, topological insulators (TIs) like  $\text{Bi}_2\text{Te}_3$  and  $\text{Bi}_2\text{Se}_3$  are attracting tremendous interest. After their theoretical prediction as three-dimensional TIs<sup>1–3</sup> and experimental confirmation as a new state of quantum matter with an insulating bulk state and metallic Dirac surface states,<sup>4–6</sup> much effort has been devoted to confirm the topological surface states (TSS) from the viewpoint of transport measurements.<sup>7–9</sup> However, electron transport properties of  $\text{Bi}_2\text{Se}_3$  and  $\text{Bi}_2\text{Te}_3$  have been always plagued by bulk conduction from the conduction band or intentional and unintentional impurity doping in the bulk samples or cleaved flakes.<sup>10–12</sup> Recently, it has been proved that ultrathin films with intrinsic TI properties can be achieved by using molecule beam epitaxy (MBE) growth, with less influence from the bulk conduction on the transport properties.<sup>13</sup>

Although oxide-gated field-effect transistors have been used as a tool to tune the Fermi level into the “topological” region for observing the surface conduction of TIs,<sup>10–12</sup> there is no definite evidence for ambipolar transport on TI single crystals or flakes by using oxide dielectrics. Electric-double-layer transistors (EDLTs) using ionic liquids (ILs) as gate dielectrics are known to be more efficient in tuning the Fermi energy  $E_F$  of solids.<sup>14–20</sup> The electric double layer (EDL) formed at liquid/solid (L/S) interfaces, functioning as nanogap capacitors with a huge capacitance, can effectively accumulate or deplete charge carrier over a large range, resulting in the progresses in electrostatic modulation of interfacial electron states,<sup>18,19</sup> like electric-field-induced

superconductivity in  $\text{SrTiO}_3$  and  $\text{ZrNCl}$ .<sup>15,16</sup> Therefore, the EDLTs based on such functionalized L/S interfaces might offer a possibility to tune the electronic states and the  $E_F$  of solids over a wide range and provide us an opportunity not only to realize the ambipolar transport but also to understand the fundamental physical properties of Dirac materials like graphene<sup>21</sup> and TIs. Another advantage of the EDLTs is their ease for device fabrication processes, where just dropping liquid on film surfaces allows us to make high-performance transistors without complicated and “dirty” lithography processes (TIs are very chemically sensitive to  $\text{H}_2\text{O}$  and organic solvents).

In this Letter, combining the advantages of the high-quality ultrathin  $\text{Bi}_2\text{Te}_3$  epitaxial films and functionalized EDL interfaces gated by IL dielectrics, we demonstrate an ambipolar operation and the modulation of the electronic states of TI ultrathin films.  $\text{Bi}_2\text{Te}_3$  films with atomically flat surfaces were grown by molecular beam epitaxy (MBE) in a layer-by-layer mode.<sup>13</sup> A Hall bar configuration with a channel size of  $600\ \mu\text{m} \times 200\ \mu\text{m}$  was patterned by shadow mask patterning processes on a smooth  $\text{Bi}_2\text{Te}_3$  film. After bonding Au wires on Ti/Au electrodes and installing a Pt plate as the gate electrode, both the channel and the Pt electrode were immersed in a small drop of IL (DEME-TFSI) to form a typical liquid-gated EDL transistor. We stress that the whole process is water-free and the exposure of the TI film to the atmosphere is as short as possible during the device fabrication.

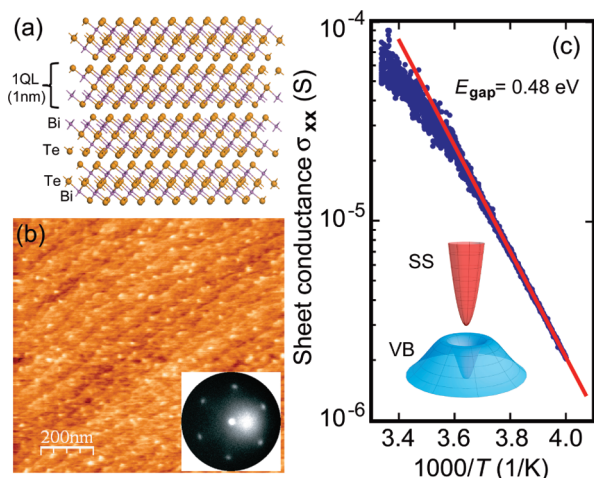
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With the same Hall bar pattern, the transport measurements of  $\text{Bi}_2\text{Te}_3$  EDLTs, including the transfer characteristics, the longitudinal sheet resistance  $R_{xx}$  and the Hall coefficient  $R_H$ , were simultaneously measured in a Physical Property Measurement System (PPMS) combined with a semiconductor parameter analyzer (Agilent 5270B). In order to avoid any possible interfacial electrochemistry between the IL and  $\text{Bi}_2\text{Te}_3$  channel, transport measurements were mainly performed at 220 K and below, where it has been proved that the interfacial chemistry is significantly suppressed by cooling.<sup>22</sup>

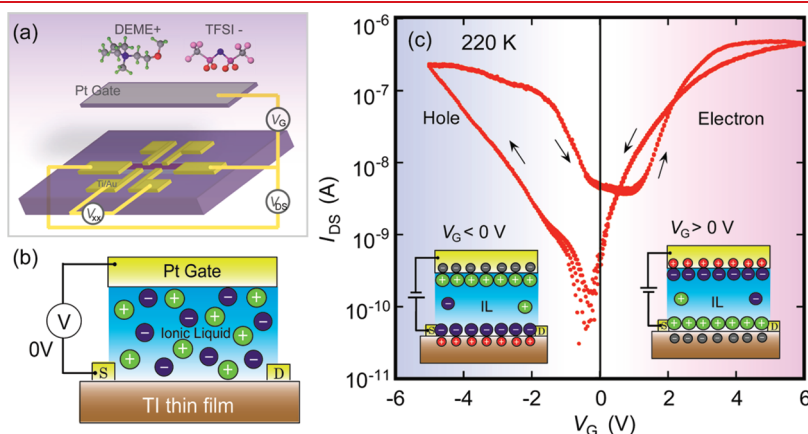
As shown in Figure 1a, atomic layers with a Te–Bi–Te–Bi–Te stacking sequence form a unique quintuple layer (QL) along the



**Figure 1.** (a) Schematic diagram of the crystal structure of  $\text{Bi}_2\text{Te}_3$ . The weak van der Waals bonding between two adjacent QLs and the strong ionic bonding inside the QLs determine that such a layered system is naturally suitable for realizing a two-dimensional atomically flat surface, which is critical for a transistor channel. (b) An atomic force microscopy (AFM) image and a low energy electron diffraction (LEED) pattern of the as-grown  $\text{Bi}_2\text{Te}_3$  ultrathin film. (c) Temperature-dependent sheet conductance of the  $\text{Bi}_2\text{Te}_3$  film with a thickness of 5 nm. The positive temperature coefficient of the conductance ( $d\sigma_{xx}/dT > 0$ ) indicates a semiconducting transport and a band gap opening behavior of the films.

*c*-axis of the unit cell of rhombohedral  $\text{Bi}_2\text{Te}_3$ . Because of the weak van der Waals bonding between two adjacent QLs, the two-dimensional layered nature is quite suitable for achieving atomically flat surfaces,<sup>23</sup> which are critically important for the transport channel of a field effect transistor. Figure 1b shows an atomic force microscopy (AFM) image and an in situ low-energy electron diffraction (LEED) pattern of the as-grown surface of a  $\text{Bi}_2\text{Te}_3$  film. The former clearly indicates the step and terrace structures with a monolayer height (1QL,  $\sim 3$  Å), whereas the latter shows the good crystalline quality of the ultrathin epitaxial film, ensuring the suitability for an EDLT channel. The transport behavior of an as-grown  $\text{Bi}_2\text{Te}_3$  thin film<sup>13,24</sup> with a thickness of  $\sim 5$  nm was investigated before dropping IL. As shown in the plot of the sheet-conductance versus inverse temperature ( $\sigma_{xx}-1/T$ ) in Figure 1c, the positive temperature coefficient of the sheet conductance ( $d\sigma_{xx}/dT > 0$ ) clearly suggests the semiconducting transport behavior of the  $\text{Bi}_2\text{Te}_3$  ultrathin film. Such a behavior was observed in all the ultrathin films we have measured (with thickness of 3–5 nm), implying that the semiconducting transport is reproducible and originates from the intrinsic properties of the ultrathin films. By fitting the  $\sigma_{xx}-1/T$  plot with the Arrhenius relationship  $\sigma_{xx} = \sigma_0 \exp(-E_a/kT)$ , the activation energy  $E_a$  of the conductivity (roughly can be regarded as the band gap of the film) was estimated as  $E_a = E_{\text{gap}} = 0.48$  eV. The value is neither zero, as appropriate for the gapless Dirac cone with surface states nor 0.17 eV between conduction band (CB) and valence band (VB) in bulk crystals, suggesting a band gap opening of the  $\text{Bi}_2\text{Te}_3$  film (demonstrated in the inset of Figure 1c). Such a large band gap opening between the conduction band and the valence band has been observed in ultrathin TI films with a value around 0.3 eV by using photoemission spectroscopy.<sup>13</sup> The present result confirms the large gap opening in the ultrathin films of  $\text{Bi}_2\text{Te}_3$  by means of transport experiment. The observed large resistance and semiconducting transport behavior of the  $\text{Bi}_2\text{Te}_3$  film suggests that the Fermi level  $E_F$  of the nonbiased TI ultrathin film is located inside the opened band gap.

Applying the IL as the dielectric for EDLTs (a schematic diagram is shown in Figure 2a,b) allows us to tune the  $E_F$  and to realize ambipolar transport in the semiconducting TI ultrathin films. Figure 2c shows the transfer characteristics (source–drain

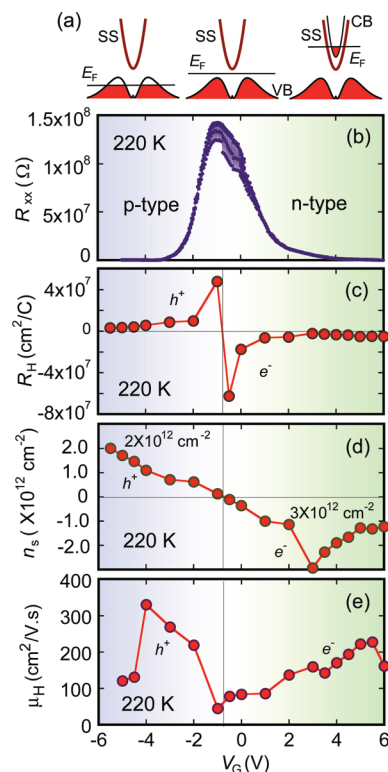


**Figure 2.** (a) Schematic diagram and (b) cross section of a liquid-gated EDL transistor based on a  $\text{Bi}_2\text{Te}_3$  film. (c) Transfer characteristics ( $I_{DS}-V_G$ ) of an EDLT based on  $\text{Bi}_2\text{Te}_3$  ultrathin films at 220 K, showing the ambipolar behavior in transport. Inset: schematic diagram of electron accumulation ( $V_G > -0.3$  V) and hole accumulation ( $V_G < -0.3$  V) in EDLTs. The transfer characteristics are very reproducible and the curves in three consecutive  $V_G$  scans nearly overlap with each other.

current  $I_{DS}$  as a function of gate-voltage  $V_G$ ) of the  $\text{Bi}_2\text{Te}_3$  EDLT at 220 K. From the schematic inset in Figure 2c, one can clearly see that with the increase of  $V_G$  in the positive direction, cations are accumulated right above the film surface and induce the similar amount of electrons in the film, resulting in a dramatic increase of the  $I_{DS}$  with electron conduction. On the other hand, when the TI channel is negatively biased, holes are correspondingly accumulated at the interface associated with the increasing  $I_{DS}$ . The ON–OFF ratio in the  $I_{DS}$  for both hole and electron accumulations is more than 3 orders of magnitude, implying that the electronic states of the channel can be modulated over a wide range. The transfer characteristics in the same devices are very reproducible and the curves of three consecutive scans are almost overlapped with each other. The observed hysteresis may be attributed to the slow ion motion (slow polarization relaxation of liquid dielectric) at 220 K and the interfacial trap states. In order to verify the reproducibility, we made several devices on different batches of ultrathin films. As shown in Figure S1 in Supporting Information, similar ambipolar transfer characteristics have been observed in these  $\text{Bi}_2\text{Te}_3$  EDLTs.

The  $V_G$  dependent sheet resistance  $R_{xx}$  in  $\text{Bi}_2\text{Te}_3$  EDLTs at 220 K, shown in Figure 3b, exhibits a sharp peak with a value more than ten mega-ohms at a low  $V_G$  near zero and decays to several kilo-ohms at higher  $V_G$ . Such a sharp peak in  $R_{xx}$  resembles the field-effect induced ambipolar transport in graphene<sup>21,23</sup> and organic semiconductors.<sup>25,26</sup> The  $R_{xx}$  decreases with the increasing bias within a voltage window of  $\Delta V_G = \pm 2$  V, which is also similar to the transport behavior of graphene-based transistors<sup>23</sup> and can be qualitatively explained by electron filling into the  $\text{Bi}_2\text{Te}_3$  band structure. As schematized in Figure 3a, when the gate is negatively biased and holes are accumulated in the  $\text{Bi}_2\text{Te}_3$  film, the Fermi energy ( $E_F$ ) is supposed to be tuned to the VB (left diagram in Figure 3a). In contrast, electrons are accumulated when the channel is positively biased, and the  $E_F$  is supposed to be shifted to the SS or even up to the conduction band (right diagram). When the bias is near zero, the Fermi level sits inside the opened band gap, resulting in a semiconducting behavior. We note that the charge neutrality point is located at  $V_G = -0.3$  V rather than the theoretical value 0 V, implying that the film is electron-doped due to some impurities and interfacial defects.

Figure 3c–e shows Hall effect measurements for various biases at 220 K. One can see from Figure 3c that the Hall coefficient  $R_H$  has opposite signs ( $R_H < 0$  for electrons and  $R_H > 0$  for holes) on different sides from the insulating point ( $V_G = -0.3$  V). This behavior directly proves the scenario that the  $E_F$  is tuned between VB and TSS (or CB) by the electric field, leading to p-type and n-type conduction, respectively. As shown in Figure 3d, away from the n–p transition point at  $V_G = -0.3$  V, the sheet carrier density  $n_s = 1/R_H|e|$  ( $n_s$  is the sheet carrier concentration and  $e$  is the electron charge) in the accumulation layer increases with the bias  $V_G$ . Similarly to the increase of the  $\sigma_{xx}$  (decrease in the  $R_{xx}$ ), the  $n_s$  increases linearly with the increasing bias within the  $\Delta V_G$  window of  $\pm 2$  V. For a larger  $V_G$ , the  $n_s$  exhibits a nonmonotonic behavior and starts to saturate by showing a pronounced maximum value. Similar behavior has been observed in EDLTs based on ZnO and organic semiconductors, which was proved to be related to the limitation of the chemical potential window of the IL.<sup>19</sup> The asymmetric behavior for the carrier ( $e^-$  or  $h^+$ ) accumulation might result from two possibilities: one is the asymmetry in the band structures and density of states of VB and TSS (or CB), and the other is the variation in the ion accumulation (cations and anions) at the EDL



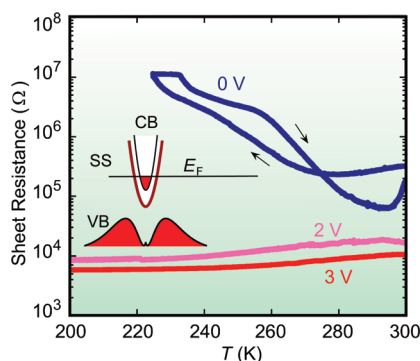
**Figure 3.** (a) Schematic band structure of the negatively biased (left), zero-biased (middle), and positively biased (right)  $\text{Bi}_2\text{Te}_3$  film. (b) The sheet resistance  $R_{xx}$  (c) the Hall coefficient  $R_H$  (d) the carrier density  $n_s$ , and (e) the Hall mobility  $\mu_H$  of an EDLT based on an ultrathin  $\text{Bi}_2\text{Te}_3$  film, as a function of the  $V_G$  at 220 K.

interfaces with opposite biases. The estimated Hall mobilities  $\mu_H = \sigma_s/|e|n_s$ , shown in Figure 3e, with a maximum value around  $300 \text{ cm}^2/\text{V}\cdot\text{s}$  for both electrons and holes, was not so high as those reported in the bulk crystals,<sup>27</sup> probably due to interface scattering from defects and lattice mismatch in such an ultrathin film.

In order to confirm that the  $E_F$  is really tuned up to the surface states and even to the conduction band from the opened band, we measured the temperature-dependent sheet resistance ( $R_{xx}-T$  curve) of the film under a positive bias with electron accumulation. Figure 4 shows the  $R_{xx}-T$  curve from 300 down to 200 K. In contrast to the semiconducting behavior in the zero-bias case (blue line, showing wiggles, possibly due to the supercooling of IL), the resistance of positively biased  $\text{Bi}_2\text{Te}_3$  films ( $V_G = +2$  and  $+3$  V, purple and red lines, respectively) gradually decreases with decreasing temperature. It clearly exhibits a metallic behavior and an absolute conductance larger than the quantum conductance ( $e^2/h$ ), indicating that the Fermi level is moved up and reaches at least the surface states at the  $V_G$  of  $+2$  V. The further decrease in resistance at  $+3$  V might suggest that  $E_F$  further moves up to the bottom of the CB band. So far, due to the large contact resistance below 200 K, the transport measurements were mainly carried out above this temperature to ensure reliability.

By simply assuming that all the carriers uniformly exist in the film with a thickness of 5 nm, the 3D carrier density can be deduced as  $2 \times 10^{17} \text{ cm}^{-3}$  with which the films show an insulating conduction. However, once a large electric field is applied, the carriers are resultingly accumulated in the channel and the thickness of the accumulation layer (the penetration depth of





**Figure 4.** Temperature-dependent resistance of the  $\text{Bi}_2\text{Te}_3$  EDLT with zero and positive biases. In contrast to the semiconducting behavior in zero-bias case (blue curve), the  $R_{xx}-T$  plot of positively biased  $\text{Bi}_2\text{Te}_3$  films ( $V_G = +2$  V, purple curve) shows a metallic behavior with a conductance larger than the quantum conductance ( $e^2/h$ ), indicating that the Fermi level has reached the surface states. With increasing the bias to +3 V, further decrease of the  $R_{xx}$  might suggest that the Fermi level moved up and touches the bottom of the CB.

applied electric field) decreases. It has been well-known in field effect transistors that the screening length decreases (the thickness of accumulation layer) with increase of carrier density. In the case of another layered material ( $\text{ZrNCl}$ ), the screening length was estimated to be about 1–2 nm.<sup>16</sup> This consideration allows us to roughly assume the charge accumulation layer in the  $\text{Bi}_2\text{Te}_3$  film as 2 nm. The 3D carrier density under the high electric field can be as large as  $1 \times 10^{19} \text{ cm}^{-3}$ , deduced by dividing the sheet carrier density  $n_s = 2 \times 10^{12} \text{ cm}^{-2}$  with the estimated thickness (2 nm). Note that only by assuming such a thickness, the 3D carrier density can be reasonably high and sufficient to induce the metallic behavior in the accumulated channel of EDLTs. Further systematic experimental investigations are necessary to clarify the thickness dependent transport and further band filling of the TSS (CB) band as well as resulting low temperature transport in  $\text{Bi}_2\text{Te}_3$  ultrathin films by means of liquid gating.

In conclusion, with the IL-gated EDLTs, we demonstrated ambipolar transport with a large ON-OFF ratio in ultrathin  $\text{Bi}_2\text{Te}_3$  films and modulated the electronic properties of the films with electric fields. Ambipolar transistor operation with an ON-OFF ratio close to  $10^3$  was not only observed in the transfer characteristics of  $\text{Bi}_2\text{Te}_3$  EDLTs but also confirmed by the sign change of the Hall coefficients in Hall measurements. The EDLTs might be commonly applicable to all types of topological insulator films for effective tuning of  $E_F$  in the band structure. Such IL/TI heterostructures involving these intriguing Dirac materials present a new exciting direction in theoretical and experimental researches.

## ■ ASSOCIATED CONTENT

**Supporting Information.** Additional information. This material is available free of charge via the Internet at <http://pubs.acs.org>.

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